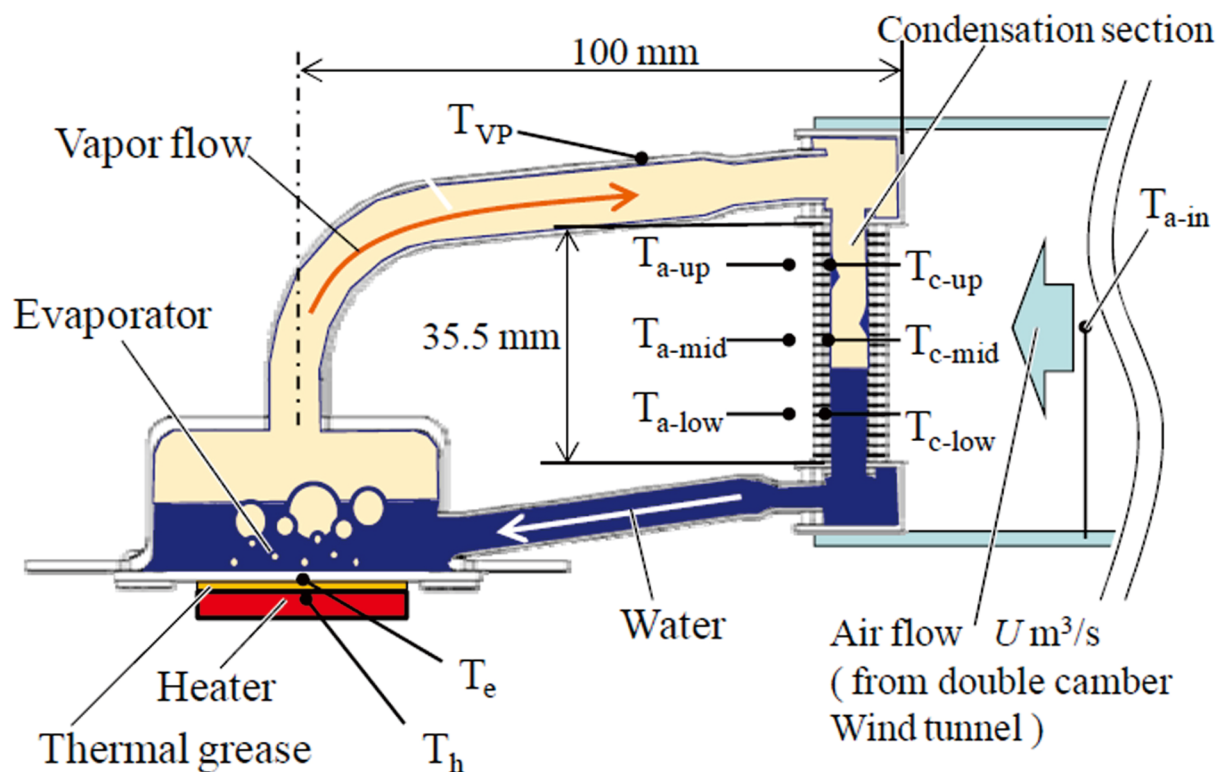


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TABLE OF CONTENTS

Volume 3 Number 4

December 2013

Effect of Non-Condensable Gas Leakage on Long Term Cooling Performance of Loop Thermosyphon

H. Toyoda, Y. Kondo.....131

Numerical Analysis of Printed Circuit Board with Thermal Vias: Heat Transfer Characteristics under Nonisothermal Boundary Conditions

Y. Koito, Y. Kubo, T. Tomimura.....136

STAR CCM+ CFD Simulations of Enhanced Heat Transfer in High-Power Density Electronics Using Forced Air Heat Exchanger and Pumped Fluid Loop Cold Plate Fabricated from High Thermal Conductivity Materials

K. R. Anderson, M. Devost, W. Pakdee, N. Krishnamoorthy.....144

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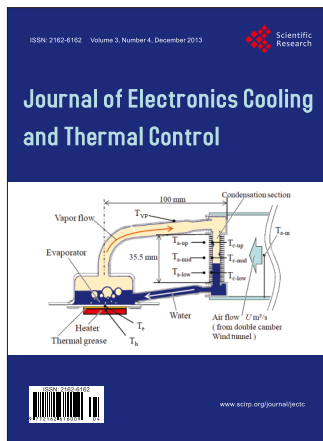
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